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ABSTRACTS DUE - MARCH 16, 2026

InterPACK 2026

The International Technical Conference on Packaging and Integration
of Electronic and Photonic Microsystems

October 26 - 29, 2026

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InterPACK is the leading global forum for cutting-edge research, development, manufacturing, and applications in electronics packaging and heterogeneous integration.

As the flagship conference of the ASME Electronic and Photonic Packaging Division (EPPD), InterPACK brings together the full systems ecosystem — from advanced materials and thermal management to next-generation computing architectures and intelligent, connected devices. The program spans Heterogeneous Integration, Servers of the Future, Edge and Cloud Computing, Internet of Things, Additive and Printed Electronics, Flexible and Wearable Electronics, Photonics and Optics, Power Electronics, Energy Conversion and Storage, and Autonomous, Hybrid, and Electric Vehicles.

TECHNICAL TRACKS

Track 1 | Heterogeneous Integration

Track 2 | Data Center, Modular Edge Systems, and Information Storage Systems

Track 3 | Electronic Packaging for Extreme Environments

Track 4 | Power/RF Electronics and Photonics

Track 5 | Nanoscale heat transfer, Multiscale Thermal Transport and Energy Storage

Track 6 | Flexible, Wearable and Printed Electronics

Track 7 | Intelligent Modeling, Simulation, and Automation Systems

Track 8 | Interactive Presentations

Track 9 | Micro/Nano Mechatronics, Microelectronics, Microelectrochemical Systems, and their Applications of Internet of Things

Visit the conference website for more information: <https://event.asme.org/InterPACK>

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